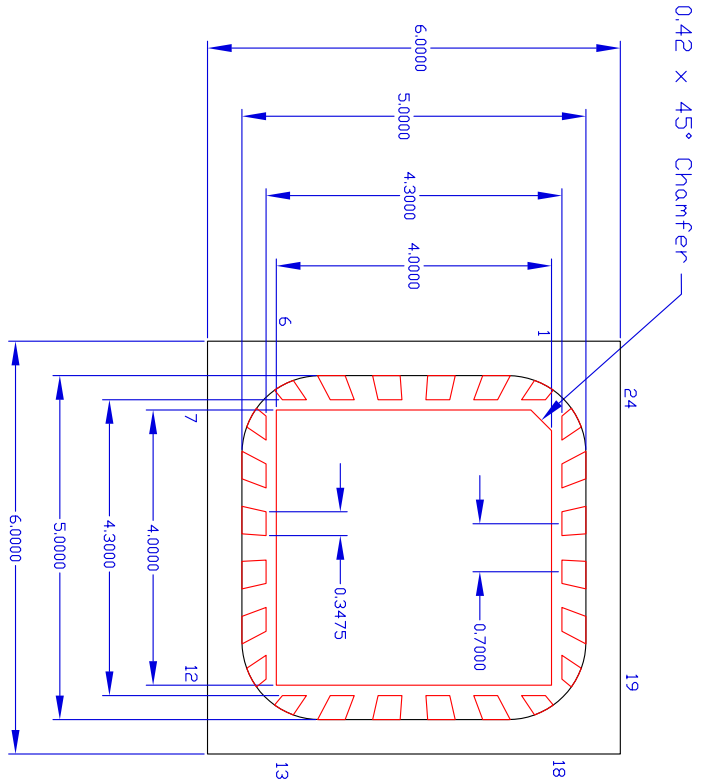
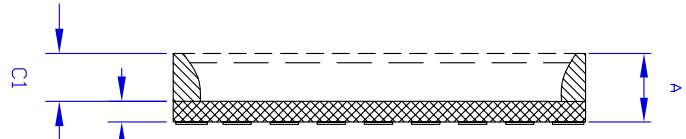


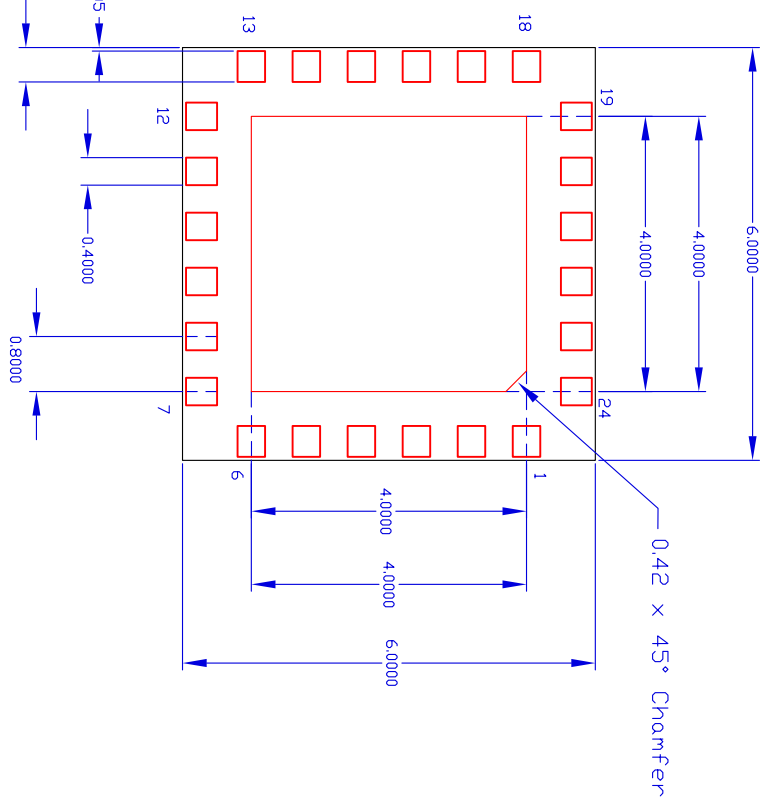
TOP VIEW



SIDE VIEW

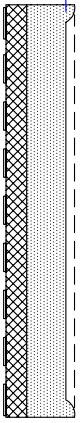


BOTTOM VIEW



Cavity wall
variance
0.05~0.15

SIDE VIEW



HEIGHT TABLE			
SERIES	C1	C2	A
A-QFN	0.63	0.27	0.90
A-TQFN	0.38	0.27	0.65
TOL	+/- 0.10	+/- 0.05	+/- 0.15

OTHER SIZES AVAILABLE

Note:

1. Organic substrate
2. Cavity Dam: Hysol FP4451TD
3. Pads: Cu/Ni/Au
4. Copper Thickness: 12µm~18µm (0.5~0.7mil)
5. Bonding Pad Gold Thickness: 1.3µm (50 micro-inch)
6. PCB Pads Gold Thickness: 0.13µm (5 micro-inch)
7. Nickel Thickness: 38µm (150 micro-inch)
8. All Dimensions Are mm

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TOLERANCES UNLESS NOTED:		APPROVALS		DATE	
X.XX	±	DRAWN		11/29/08	
X.XXX	±	ENG		TA	
X.XXXX	±	MFG			
ALL DIMENSIONS ARE IN: <input type="checkbox"/> INCHES <input type="checkbox"/> MILLIMETERS		TITLE			
THIRD ANGLE PROJECTION:		24-LEAD 6MM P=0.80MM			
SCALE	SIZE	DRAWING NO.		REV	
NONE	A	482410		A	
DO NOT SCALE DRAWING		SHEET		1 OF 1	

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